

Type number	Package	Package description	Total product weight
74AHCT541D	SOT163-1	SO20	520.74945 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935261963112	12	1	260	30 s	1	240	20 s	3	Suzhou, China; Nijmegen, Netherlands; Bangkok, Thailand	IMG
935261963118	10	1	260	30 s	1	240	20 s	3	Nijmegen, Netherlands; Bangkok, Thailand; Suzhou, China	IMG

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Adhesive	Filler	Silver (Ag)	7440-22-4	3.48034	77.86000	0.66833
		Polymer	Acrylic resin	Proprietary	0.67855	15.18000
		Resin system	Proprietary	0.31111	6.96000	0.05974
		subTotal		4.47000	100.00000	0.85837
Die	Doped silicon	Silicon (Si)	7440-21-3	0.46205	100.00000	0.08873
		subTotal		0.46205	100.00000	0.08873
Lead Frame Material	Copper alloy	Copper (Cu)	7440-50-8	152.56004	97.47000	29.29625
		Iron (Fe)	7439-89-6	3.75648	2.40000	0.72136
		Phosphorous (P)	7723-14-0	0.04696	0.03000	0.00902
		Zinc (Zn)	7440-66-6	0.15652	0.10000	0.03006
		subTotal		156.52000	100.00000	30.05669
Mould Compound	Additive	Non hazardous	Proprietary	16.84621	4.70000	3.23499
	Filler	Silica fused	60676-86-0	283.15970	79.00000	54.37542
	Flame retardant	Magnesium Hydroxide (Mg(OH)2)	1309-42-8	21.50580	6.00000	4.12978
	Pigment	Carbon black	1333-86-4	0.71686	0.20000	0.13766
	Polymer	1,4-bis(methoxymethyl)benzene/phenol copolymer	26834-02-6	14.33720	4.00000	2.75319
		Non hazardous	Proprietary	14.69563	4.10000	2.82202
		Tetramethylbiphenyl diglycidyl ether	85954-11-6	7.16860	2.00000	1.37659
	subTotal		358.43000	100.00000	68.82965	
Pre-Plating	Pure metal layer	Gold (Au)	7440-57-5	0.01950	3.00000	0.00374
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.59995	92.30000	0.11521
		Palladium (Pd)	7440-05-3	0.02015	3.10000	0.00387
		Silver (Ag)	7440-22-4	0.01040	1.60000	0.00200
		subTotal		0.65000	100.00000	0.12482
Wire	Pure metal	Copper (Cu)	7440-50-8	0.21741	100.00000	0.04175
		subTotal		0.21741	100.00000	0.04175

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